

Title (en)

ONE-STEP PRETREATMENT METHOD OF METALLIC SUBSTRATES FOR METAL COLD FORMING

Title (de)

EINSTUFIGES VORBEHANDLUNGSVERFAHREN FÜR METALLISCHE SUBSTRATE ZUR KALTUMFORMUNG VON METALLEN

Title (fr)

PROCÉDÉ DE PRÉTRAITEMENT EN UNE ÉTAPE DE SUBSTRATS MÉTALLIQUES POUR FORMAGE À FROID DE MÉTAL

Publication

**EP 4110889 A1 20230104 (EN)**

Application

**EP 21706961 A 20210225**

Priority

- EP 20159323 A 20200225
- EP 2021054657 W 20210225

Abstract (en)

[origin: WO2021170707A1] The present invention relates to method for pretreatment of a metallic substrate for a subsequent metal cold forming process, said method comprising at least steps (1) and (2) and optionally step (3), namely providing at least one substrate having at least one surface at least partially made of at least one metal (1), contacting the at least one surface of the substrate provided in step (1) with an aqueous lubricant composition (A) having a pH value below 2.0 and comprising besides water oxalate anions (a1), thiosulfate anions (a2), chloride anions (a3), at least one film-forming polymer (a4), which is a homopolymer and/or copolymer being prepared by polymerization of at least one ethylenically unsaturated monomer, at least one wax (a5), and fluoride anions and/or bifluoride anions (a6), and optionally drying the coating film obtained after having performed step (2), a pretreated metallic substrate obtainable by the aforementioned inventive method, a method of cold forming of a metallic substrate including a step of subjecting the inventive pretreated metallic substrate to a cold forming process, an aqueous lubricant composition (A) as defined above and a master batch for preparing the aqueous composition (A).

IPC 8 full level

**C10M 173/02** (2006.01); **C10M 177/00** (2006.01); **C23C 22/46** (2006.01); **C23C 22/83** (2006.01); **C23G 1/00** (2006.01); **C23G 1/08** (2006.01);  
**C10N 30/12** (2006.01); **C10N 40/20** (2006.01); **C10N 50/02** (2006.01); **C10N 70/00** (2006.01); **C10N 80/00** (2006.01)

CPC (source: EP US)

**C10M 173/02** (2013.01 - EP US); **C10M 177/00** (2013.01 - EP); **C23C 22/34** (2013.01 - US); **C23C 22/46** (2013.01 - EP US);  
**C23C 22/83** (2013.01 - EP); **C23G 1/00** (2013.01 - EP); **C23G 1/065** (2013.01 - US); **C23G 1/086** (2013.01 - EP); **C10M 2201/02** (2013.01 - EP);  
**C10M 2201/081** (2013.01 - EP); **C10M 2201/084** (2013.01 - EP); **C10M 2205/14** (2013.01 - EP); **C10M 2205/16** (2013.01 - EP);  
**C10M 2205/18** (2013.01 - EP); **C10M 2207/123** (2013.01 - EP); **C10M 2209/04** (2013.01 - EP); **C10M 2209/062** (2013.01 - EP);  
**C10M 2217/023** (2013.01 - EP); **C10M 2217/024** (2013.01 - EP); **C10M 2217/028** (2013.01 - EP); **C10N 2030/12** (2013.01 - EP);  
**C10N 2040/243** (2020.05 - EP); **C10N 2040/247** (2020.05 - EP); **C10N 2050/02** (2013.01 - EP); **C10N 2070/02** (2020.05 - EP);  
**C10N 2080/00** (2013.01 - EP)

Citation (search report)

See references of WO 2021170707A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

**WO 2021170707 A1 20210902**; BR 112022016708 A2 20221011; CA 3168959 A1 20210902; CN 115151627 A 20221004;  
EP 4110889 A1 20230104; MX 2022010395 A 20220907; US 2023091443 A1 20230323

DOCDB simple family (application)

**EP 2021054657 W 20210225**; BR 112022016708 A 20210225; CA 3168959 A 20210225; CN 202180016590 A 20210225;  
EP 21706961 A 20210225; MX 2022010395 A 20210225; US 202117904969 A 20210225